

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chien-Wei Chang</td> <td>06/18/2007</td> </tr> <tr> <td>Ting-Hao Lin</td> <td>06/18/2007</td> </tr> <tr> <td>Jen-Fang Chang</td> <td>06/18/2007</td> </tr> <tr> <td>Yu-Te Lu</td> <td>06/18/2007</td> </tr> <tr> <td>Chia-Chi Lo</td> <td>06/18/2007</td> </tr> </tbody> </table>		Name	Execution Date	Chien-Wei Chang	06/18/2007	Ting-Hao Lin	06/18/2007	Jen-Fang Chang	06/18/2007	Yu-Te Lu	06/18/2007	Chia-Chi Lo	06/18/2007
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Yu-Te Lu	06/18/2007												
Chia-Chi Lo	06/18/2007												
RECEIVING PARTY DATA													
Name:	Kinsus Interconnect Technology Corp.												
Street Address:	No. 1245, Junghua Rd.												
Internal Address:	Shin-Wu Shiang												
City:	Taoyuan												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11766194</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11766194								
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CORRESPONDENCE DATA													
Fax Number:	(408)867-7437												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	07158URL												
NAME OF SUBMITTER:	Jason Z. Lin												

OP \$40.00 11766194

Total Attachments: 2

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ASSIGNMENT

WHEREAS, I/we, Chien-Wei Chang, Ting-Hao Lin, Jen-Fang Chang, Yu-Te Lu and Chia-Chi Lo
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful
improvements in METHOD OF FABRICATING BOARD HAVING HIGH DENSITY CORE
(hereinafter referred to as the Invention) for which an application for United States Letters Patent was LAYER AND STRUCTURE
THEREOF

- executed on even date herewith;
- executed on _____;
- filed on _____, Serial No. _____;
- filed as PCT International Application No. _____ on _____, designating
The United States of America.;
- Patent number _____, issue on _____.

WHEREAS, KINSUS INTERCONNECT TECHNOLOGY CORP.
whose post office address is No. 1245, Junghua Rd., Shin-Wu Shiang, Taoyuan, Taiwan
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the invention that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Director of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor: Chien-Wei Chang Dated this 18th day of June, 2007 at Taiwan
No. 29, Chang-Ching 5th St.,
Yang-Mei Town,
Taoyuan Hsien,
Taiwan
Chien Wei Chang
Signature

Assignor: Ting-Hao Lin Dated this 18th day of June, 2007 at Taiwan
16F, No. 80, Lane 134,
Sec. 3, Hsin-Yi Road, Taipei,
Taiwan
Ting-Hao Lin
Signature

Assignor: Jen-Fang Chang Dated this 18th day of June, 2007 at Taiwan
12F-1, No. 63, Fu-Shou Street 1,
Chungli City,
Taoyuan Hsien,
Taiwan
Jen Fang Chang
Signature

ASSIGNMENT
(SUPPLEMENTAL SHEET)

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Title: METHOD OF FABRICATING BOARD HAVING HIGH DENSITY CORE LAYER AND
Inventors: Chien-Wei Chang, Ting-Hao Lin, Jen-Fang Chang, STRUCTURE THEREOF
Yu-Te Lu, and Chia-Chi Lo

Assignor: Yu-Te Lu Dated this 18th day of June, at Taiwan
No. 93, Hsin-Chuang-Tzu, 2007
Hsin-Chuang Village, Lu-Chu Country,
Taoyuan Hsien, Taiwan

Lu yu Te
Signature

Assignor: Chia-Chi Lo Dated this 18th day of June, at Taiwan
No. 5, Lane 64,
Lung-Chuan Street,
Chungli City, Taoyuan Hsien,
Taiwan

Lo Chia Chi
Signature